

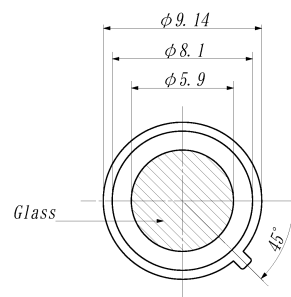
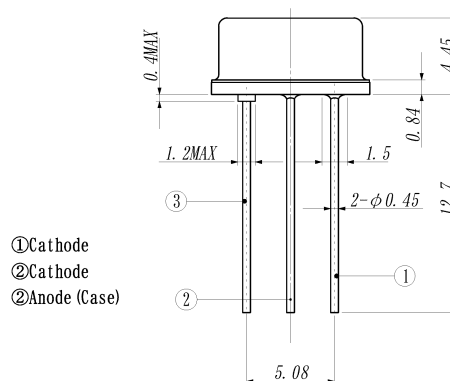
MTE8087T

Features

Ultra High Power Output
Chip Size 1.0x1.0mm
Four Wire Bonds on Die Corners
Standard 3-lead TO-39 Hermetic Package
Two Cathode Pins Must Be Externally Connected Together

Maximum Ratings (Ta=25°C)

Characteristic	Symbol	Max.	Test Condition	Unit
Forward Current	I _F	500	—	mA
Pulsed Forward Current	I _{FP}	10.00	tw=10μS, T=10mS	A
Reverse Voltage	V _R	5	—	V
Power Dissipation	P _D	1000.00	—	mW
Operating Temperature	T _{opr}	-50 ~ +100	—	°C
Storage Temperature	T _{stg}	-50 ~ +100	—	°C
Junction Temperature	T _j	100	—	°C
Soldering Temperature	T _{sol}	260	for 3 sec. max	°C



TOLERANCE ; ±0.15

Opto-Electrical Characteristics (Ta=25°C)

Characteristic	Symbol	Test Condition	Min	Typ	Max	Unit
Forward Voltage	V _F	I _F =300mA	—	1.50	2.00	V
Reverse Current	I _R	V _R =5V	—	—	10	μA
Power Output	P _O	I _F =300mA	—	50.00	—	mW
Half Intensity Beam Angle	θ	—	—	± 45°	—	deg.
Peak Wavelength	λ _p	I _F =300mA	—	870	—	nm
Spectral Line Half Width	Δλ	I _F =300mA	—	45	—	nm

MTE8087T Graphs

